

**Remarks/Arguments**

Reconsideration of this application is requested.

**Claim Status**

Claims 1-20 were presented. Claim 1 is amended. Claims 15-20, which are withdrawn from consideration as a result of a previous restriction requirement and election of claims 1-14, are canceled without prejudice. Thus, claims 1-14 are now pending.

**Claim Rejections – 35 USC 102**

Claims 1-6 and 8-14 are rejected under 35 USC 102(e) as anticipated by Hashimoto (US 2003/0124762). Claims 1, 3-7 and 11 are rejected under 35 USC 102(e) as anticipated by Fukasawa (US 6,657,282). Applicant respectfully traverses the rejections and amends claim 1 to clarify its distinction relative to Hashimoto and Fukasawa. In particular, claim 1 is amended to recite:

cutting the first substrate and the second substrate  
*simultaneously* with a *single* cutting tool.

**Hashimoto**

Hashimoto is directed to an optical device and method of manufacturing the same. According to Hashimoto, the method includes opposing a first substrate and a second substrate with spacers interposed in between. The first substrate is optically transmitting. The second substrate includes a plurality of optical elements disposed thereon. Each of the optical elements includes an optical section. Each spacer surrounds each of the optical sections. The first substrate and the second substrate are connected with the spacers interposed, and seal each of the optical sections by the first substrate and the spacers. The second substrate is separated into individual optical elements, which includes one of the sealed optical sections. (See, Hashimoto; Para. 0004-007).

Hashimoto discloses cutting the first substrate (10) with a first cutter (36), and then cutting the second substrate (20) with a second cutter (38). (See,

*Hashimoto; Fig. 4B and 4C*). In contrast, claim 1 as amended requires *simultaneous cutting* of the first substrate and the second substrate with a *single cutting tool*. (See *Specification, paragraph [0075]; Fig. 9(B)*). Thus, since Hashimoto teaches a two-step and two-cutting tool process, and not the single step (simultaneous) single cutting tool as required by claim 1, it cannot anticipate claim 1 or claims 2-6 and 8-14 dependent thereon. The rejections under 35 USC 102 should be withdrawn.

### **Fukasawa**

Fukasawa is directed to a semiconductor device having a ball grid array. According to Fukasawa, a semiconductor device has a resin package layer on a principal surface of a semiconductor chip. A plurality of bump electrodes are formed on the resin layer. The semiconductor device has a stepped surface on a top edge part such that the external shock to the edge are dissipated by the stepped surface. (See, *Fukasawa; Abstract*).

Fukasawa has at least the same deficiencies as Hashimoto. In particular, Fukasawa discloses a two-step and two-cutter method of cutting the first and second substrates. (See, *Fukasawa; Fig. 10B and 10E; Reference characters 26 and 27A*). Thus, since Fukasawa teaches a two-step and two-cutting tool process, and not the single step (simultaneous) single cutting tool as required by claim 1, it cannot anticipate claim 1 or claims 3-7 and 11 dependent thereon. The rejections under 35 USC 102 should be withdrawn.

### **Conclusion**

This application is now believed to be in condition for allowance. The examiner is invited to telephone the undersigned to resolve any issues that remain after entry of this amendment.

Appl. No. 10/724,581  
Amdt. dated December 1, 2005  
Reply to Office Action of October 3, 2005

Atty. Ref. 81754.0105  
Customer No. 26021

Any fees due with this response may be charged to our Deposit Account No.  
50-1314.

Respectfully submitted,  
HOGAN & HARTSON L.L.P.

Date: December 1, 2005

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